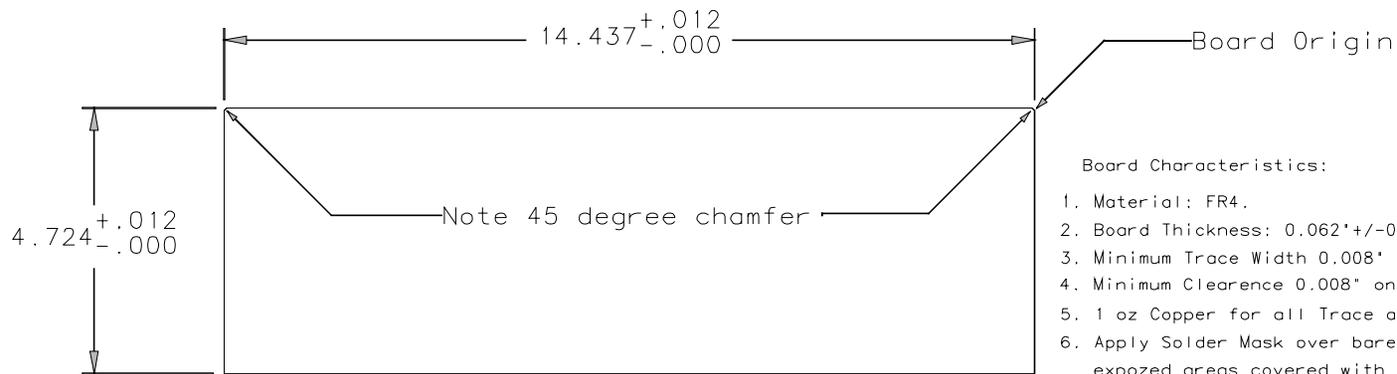


Schematic Drawing: C-2374
 Assembly Drawing: C-2376



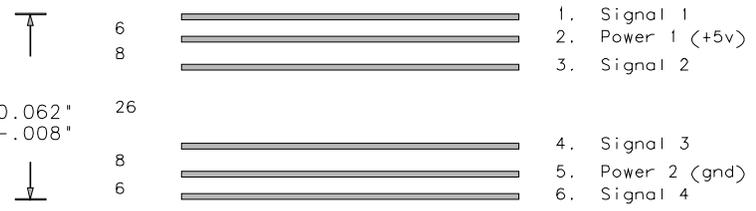
Board Characteristics:

1. Material: FR4.
2. Board Thickness: 0.062" +/- 0.008" (2.36 +/- .20mm).
3. Minimum Trace Width 0.008" on all layers.
4. Minimum Clearance 0.008" on all layers.
5. 1 oz Copper for all Trace and Power Layers.
6. Apply Solder Mask over bare copper; exposed areas covered with solder.
7. Silkscreen on Both Sides
8. Interlayer spacing : as specified.
9. All hole diameter tolerances : +/- 0.002" unless specified.

AUX Card Drill Schedule (inches)

FHS	COUNT	PLATED	COMMENT
.02	1006	YES	
.0236	379	YES	Note 10.
.024	143	YES	
.033	300	YES	
.041	179	YES	
.052	2	YES	
.057	2	YES	
.106	26	YES	
.106	24	NO	
.113	6	NO	

Board Thickness +/- .008"



Note 10: This is a pressfit technology through hole tin plated with the following specification:

- 10-1. Finished hole size: 0.6mm +/- 0.05mm
- 10-2. Drilled hole size: 0.7mm +/- 0.02mm
- 10-3. Thickness of Copper plating: min 25 μm Cu
- 10-4. Thickness of tin plating: 5-15 μm Sn.

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .008			CONTRACT NO.		ENRICO FERMI INST., UNIV. OF CHICAGO ELECTRONICS DEVELOPMENT GROUP			
DO NOT SCALE DRAWING			APPROVALS	DATE	TITLE CDF L1 Auxiliary Board Specification Drawing			
TREATMENT	DRAWN M. Bogdan		6/29/99		CHECKED H. Sanders		6/29/99	
FINISH	ISSUED		SIZE B		FSCM NO.		DRG. NO. B-2375	
SIMILAR TO	ACT. WT	CALC. WT	SCALE 1/2		SHEET 1 of 1		REV. D	